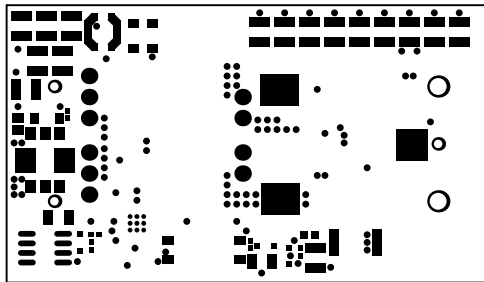
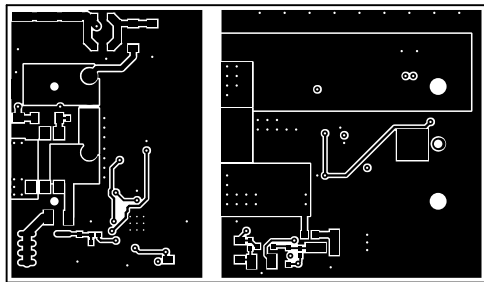


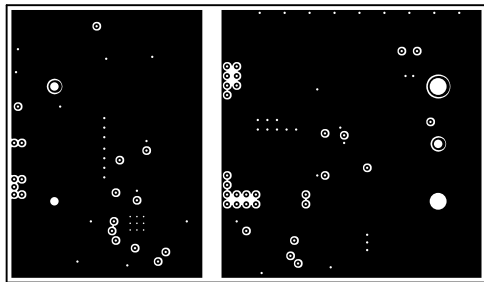
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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 9/24/2013 8:35:38 AM | TEXAS INSTRUMENTS | |



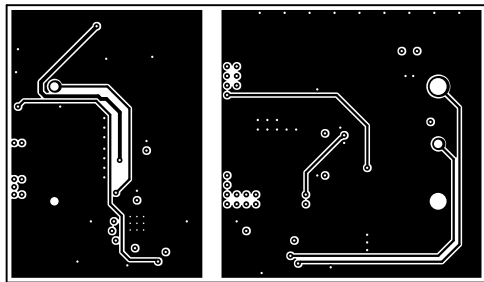
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| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 9/24/2013 8:35:39 AM | TEXAS INSTRUMENTS | |



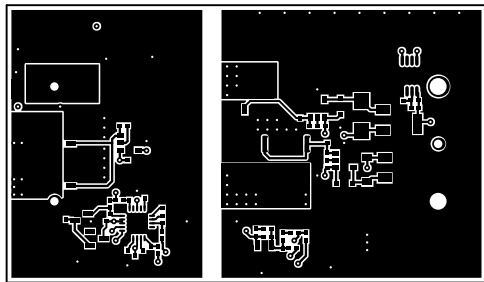
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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 9/24/2013 8:35:39 AM | TEXAS INSTRUMENTS | |



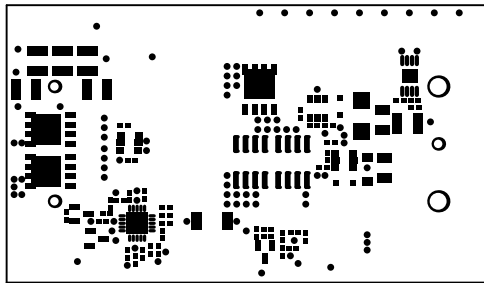
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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = M1 Board Outline | | | |
| PLOT NAME = Mid Layer 1 | GENERATED : 9/24/2013 8:35:40 AM | TEXAS INSTRUMENTS | |



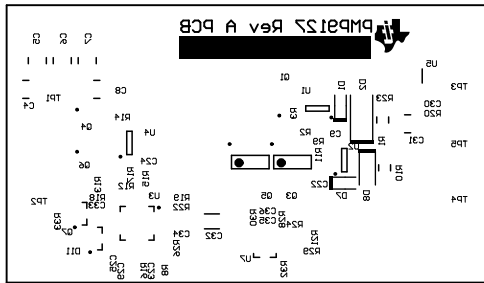
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = M1 Board Outline | | | |
| PLOT NAME = Mid Layer 2 | GENERATED : 9/24/2013 8:35:40 AM | TEXAS INSTRUMENTS | |



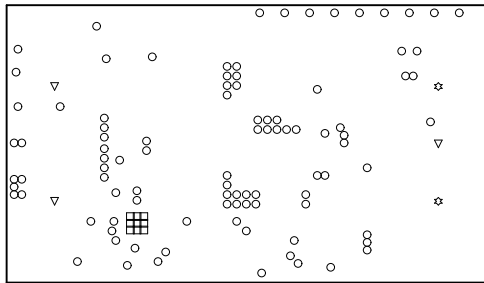
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 9/24/2013 8:35:41 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 9/24/2013 8:35:41 AM | TEXAS INSTRUMENTS | |



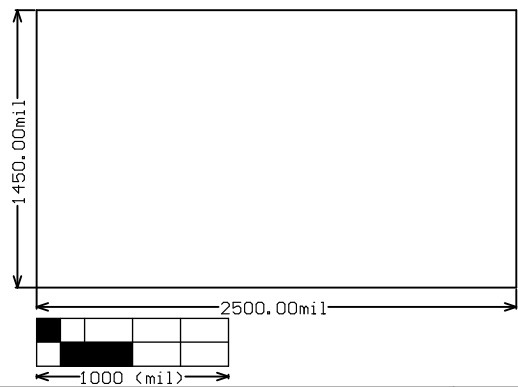
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 9/24/2013 8:35:42 AM | TEXAS INSTRUMENTS | |



| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|--------|-----------|------------------|--------|-----------|
| □ | 9 | 7.874mil (0.2mm) | PTH | Round |
| ○ | 96 | 12mil (0.305mm) | PTH | Round |
| ▽ | 3 | 43mil (1.092mm) | PTH | Round |
| ☆ | 2 | 87mil (2.21mm) | PTH | Round |
| | 110 Total | | | |

Drill Table

| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 9/24/2013 8:35:42 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9127 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 9/24/2013 8:35:43 AM | TEXAS INSTRUMENTS | |

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